



Response Under 37 CFR § 1.116  
Expedited Procedure

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Appl. No. : 10/823,970  
Applicant : OGAWA, et al.  
Filed : 13 April 2004  
Art Unit : 2818  
Examiner : Hoang, Quoc Dinh  
Attorney :  
Docket No. : SPSN-AF01215

Confirmation No. 5318

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For: SEMICONDUCTOR DEVICE HAVING  
A PAD METAL LAYER AND A LOWER METAL  
LAYER THAT ARE ELECTRICALLY  
COUPLED, WHEREAS APERTURES ARE  
FORMED IN THE LOWER METAL LAYER  
BELOW A CENTER AREA OF THE PAD  
METAL LAYER

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action dated October 31, 2006, Applicants respectfully request reconsideration of the above-identified patent application. Please consider the following amendments and remarks for allowance of the above-identified patent application.

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Serial No.: 10/823,970  
Group Art Unit: 2818